

Abstract

Present invention is a Heat sink-type cooling device for an integrated circuit comprising a base and plurality of fin extended upward. The plurality of fin is divided into more than one heat zones and said plurality of heat zone has height drop between each two zones wherein rectangular hole can also be punched on the plate end of said plurality of fin which is not connected with said base. By these heat zones with height drop between each two zones, the heat sink-type cooling device is able to match up the inner space allocation of the computer mainframe and be assembled even more easily into the computer mainframe so that heat is dispersed efficiently.